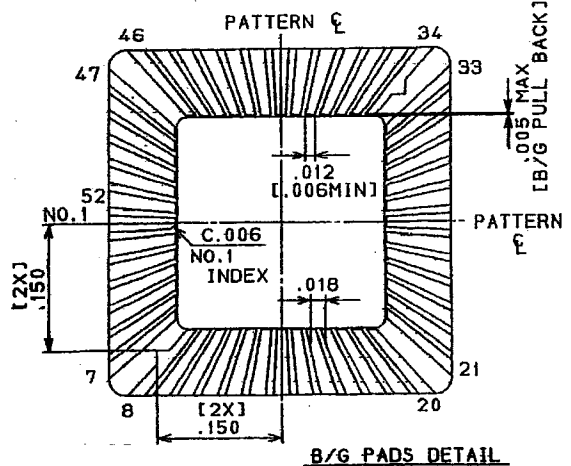
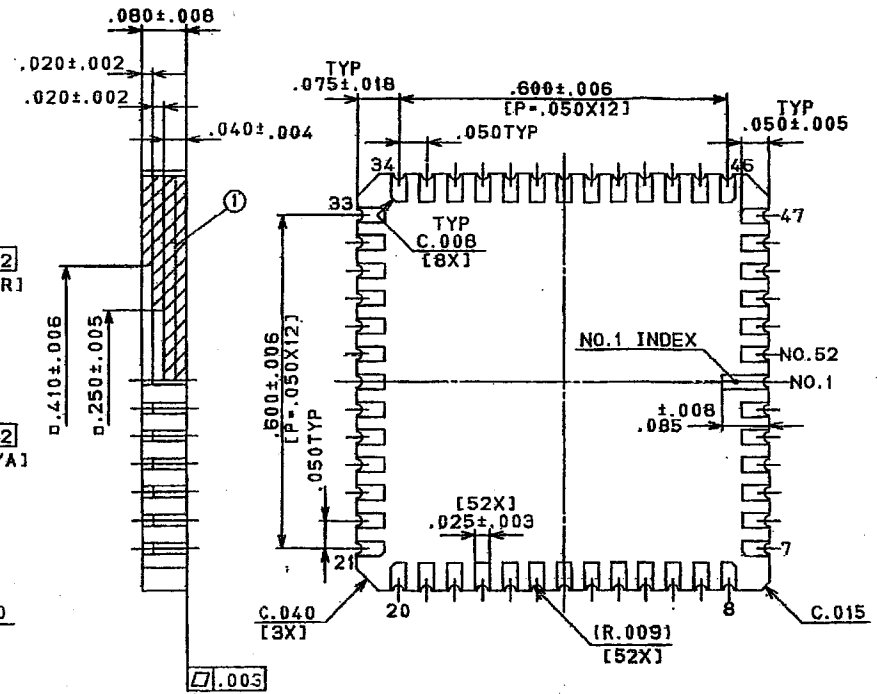
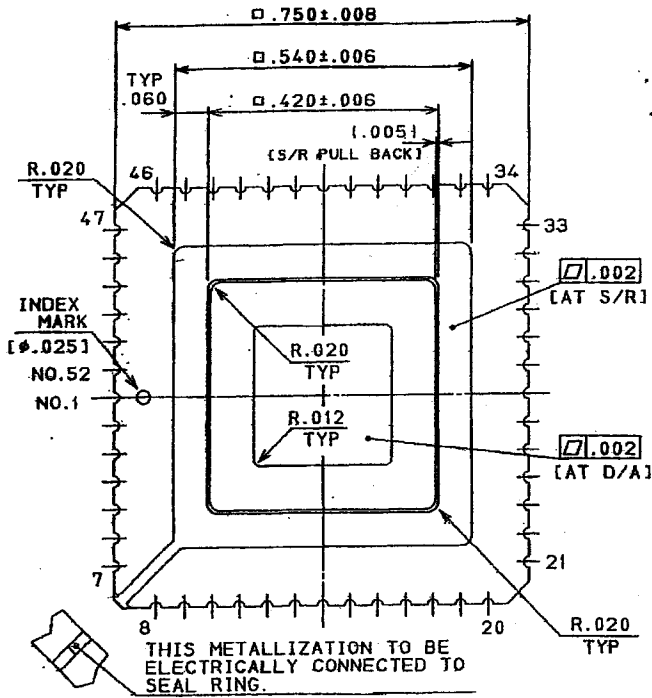


SSM P/N LCC05209



- NOTES:
1. GOLD PLATE 60~225 μ INCHES MIN 50~350 μ INCHES NICKEL.
 2. S/R & D/A PAD TO BE ELECTRICALLY ISOLATED FROM ANY LEADS.
 3. LEAD RESISTANCE:
LEAD NO.14,39 --- 100ma MAX.
ALL OTHERS --- 500ma MAX.
 4. CORNER METALLIZATION REMOVED BY GRINDING PROCESS

2					
1	CERAMIC	BLACK ALUMINA		NEW DRAWING	APR-84
Rev	Mat	Material	Description	Rev.	Description
UNLESS OTHERWISE SPECIFIED			DRAWN	K. HANAI	
N. L. T. DECIMALS .XX ± .01			CHECKED		
CUSTOMER			APPROVED	S. Maclean	
			UNIT	INCH	
			TITLE		
			52 LEAD CHIP CARRIER		
			DATE		
			1/21		

